

## **Technical Data Sheet**

MODEL NO: 170YG2-G 2.0\*1.25mm Chip LED

#### Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

### Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
GaP/GaP	Green	White diffused

## Electrical/Optical Characteristics(Ta= $25^{\circ}$ C)

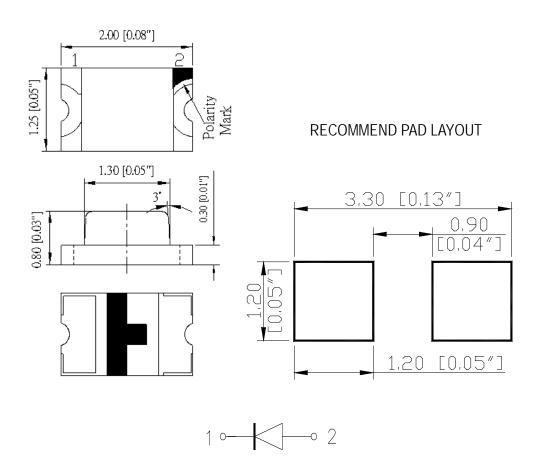
Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Max	UIIII
Wavelength at peak emission	IF=20mA	λ peak		565		nm
Dominant wavelength	IF=20mA	λd	565	570	576	nm
Spectral half bandwidth	IF=20mA	Δλ		20		nm
Forward voltage	IF=20mA	VF	1.7	2.0	2.5	V
Luminous intensity	IF=20mA	lv	5.0	15	25	mcd
Viewing angle at 50% lv	IF=10mA	2 <i>0</i> 1/2		120		Deg
Reverse current	V <sub>R</sub> =5V	lR			10	μΑ

### Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	72	mW
Forward current	lF	30	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	IFP	125	mA



## PACKAGING DIMENSIONS (mm):



#### **Precautions For Use:**

#### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

### Storage

- 1. The operation of temperature and R.H. are :  $5^{\circ}$ C  $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C}\pm5^{\circ}\text{C}$  for 15hrs.



## Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

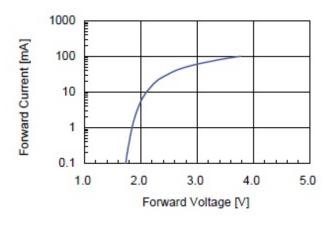


Fig 2. Relative Intensity vs. Forward Current

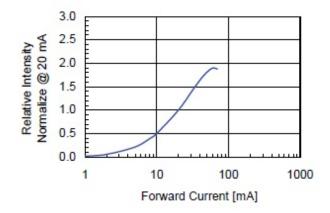


Fig 3. Forward Voltage vs. Temperature

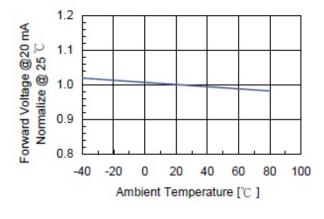


Fig 4. Relative Intensity vs. Temperature

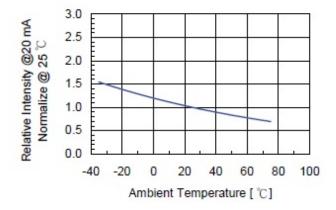
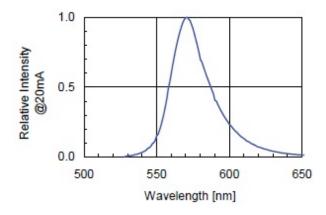
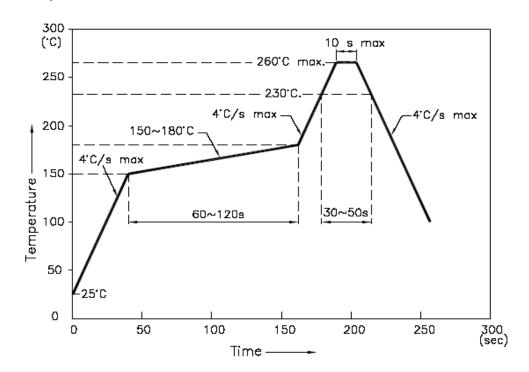


Fig 5. Relative Intensity vs. Wavelength





### ■ Reflow Temp/Time



#### NOTES:

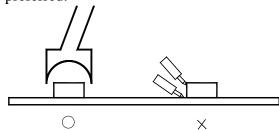
- 1. We recommend the reflow temperature  $245^{\circ}\text{C}(\pm 5^{\circ}\text{C})$ .the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

#### **■**Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

#### **■**Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.

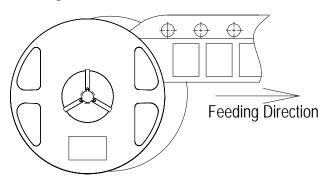


■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.

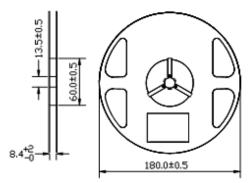


## **Packaging Specifications**

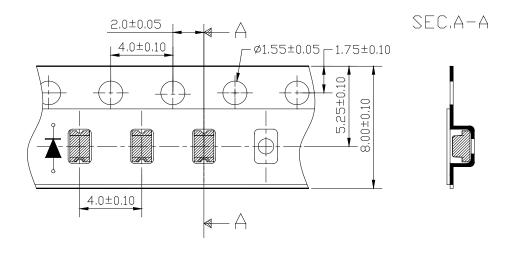
Feeding Direction



Dimensions of Reel (Unit: mm)



### Dimensions of Tape (Unit: mm)



### Arrangement of Tape

